

Operation: 沉板式 (沉深 2.0mm) D+S 结构 & 3.1Type-C 连接器 (24PIN)



ITEM NO.: MC-313C-20 (Consumer Electronics)

(L10.3×W9.15×H 3.65 & DUL SMT LOW PCB TYPE)

3.1 Type-C CONNECTORS



Technical parameter

外焊沉板 DIP+SMT

側向導入 LATERAL

精密部品 NICETY

可靠 STABILIZE

環保材質 RoHS

PROJECT

LEVEL

A[better product]

B[average product]

Electrical
PropertiesContact Rating
Initial Contact Resistance
Insulation Resistance
Withstand Voltage
There No Load
Rated Load

Durable Performance

Storage Temp

5A, 24V DC

30mΩ max.

50mΩ max.

100MΩ min.500V DC Skey/PD: 100MΩ min.300V DC

500V AC for 1 minute

350 V AC for 1 minut

6,500 Cycles

5,500 Cycles

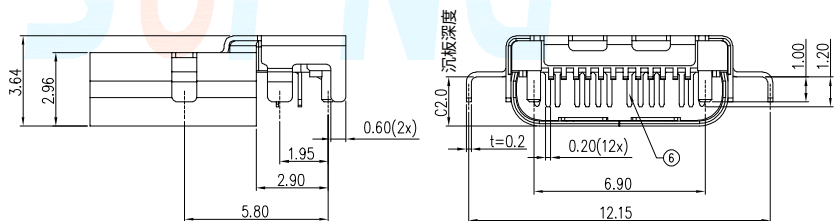
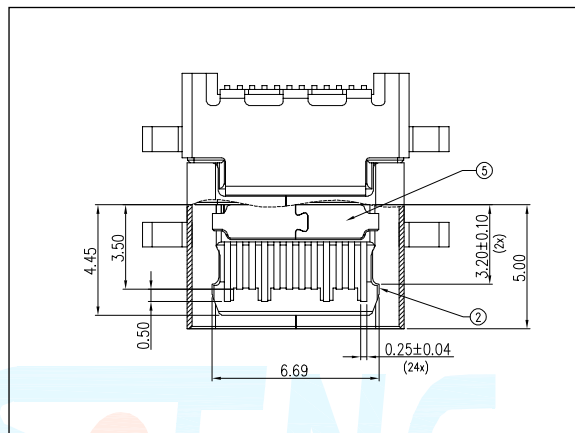
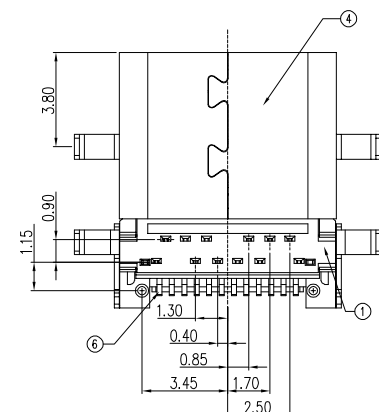
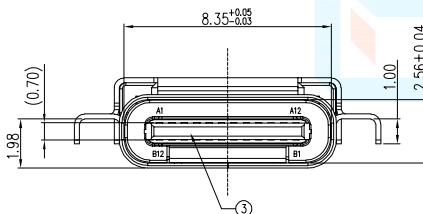
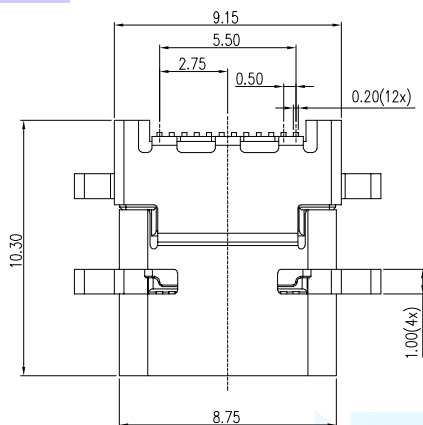
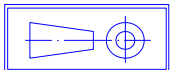
5,500 Cycles

4,500 Cycles

25°C/50%RH (Operating temperature: -35°C~+75°C)

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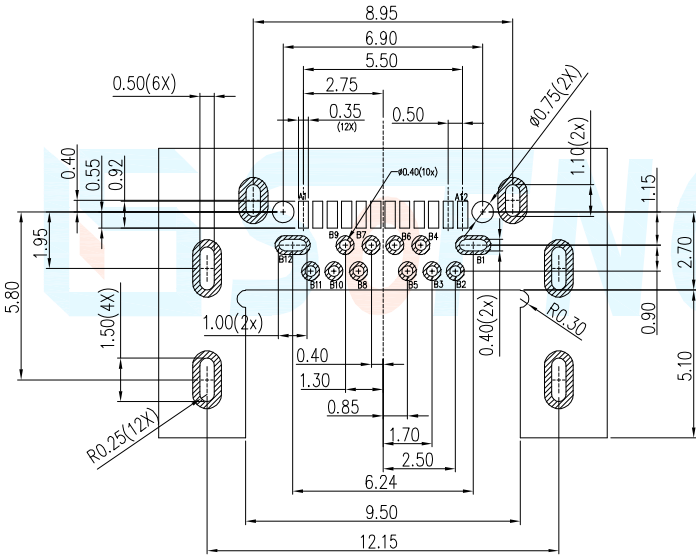
Unit:mm



Material declaration

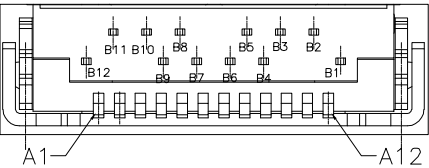
No	NAME	MATERIAL	REMARKS
①	TERMINAL HOUSING 基座	HIGH TEMPERATURE PLASTIC	BLACK/NATURE/GREEN
②	SPRING 弹片	STAINLESS 【G/F】 t=0.10	0.25 μ m Ni PLATED OVERALL;
③	IRON HOUSING 胶芯	HIGH TEMPERATURE PLASTIC	UL 94V-0,COLOR:BLACK;
④	SHELL 外壳	STAINLESS 【G/F】 t=0.30	Ni PLATED
⑤	DUST COVER 防护盖	HIGH TEMPERATURE PLASTIC	UL 94V-0,COLOR:BLACK;
⑥	CONTACT 接触端子	COPPER ALLOY 【G/F】 t=0.15	C5191R-H (1u" MIN)

Operating Force	Inward	8. 0~20. 0N. (1N.=100gram-force)	Solder-ability (Max.)	IR Reflow:255℃, 5sec.	Manual :350℃, 3sec.
	Exiting	8. 0~20. 0N. (1N.=100gram-force)			



DECIMALS	ANGLES
.X :±0.25	X.° :±1.5°
.XX :±0.15	X.X° :±1.0°
.XXX :±0.10	.XXX° :±0.5°

PIN ASSIGNMENTS



PIN	Signal NAME	Description	PIN	Signal NAME	Description
A 1	GND	Ground return	B12	GND	Ground return
A 2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A 3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A 4	V BUS	Bus Power	B 9	V BUS	Bus Power
A 5	CC1	Configuration Channel	B 8	SBU2	Sideband Use (SBU)
A 6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B 7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A 7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B 6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A 8	SBU1	Sideband Use (SBU)	B 5	CC2	Configuration Channel
A 9	V BUS	Bus Power	B 4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B 3	SSTXn2	Negative half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B 2	SSTXp2	Positive half of first SuperSpeed TX differential pair2
A12	GND	Ground return	B 1	GND	Ground return

注記 NOTICE

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